

Aliases (C0805C123J5RAC7800) SMD Comm X7R, Ceramic, 0.012 uF, 5%, 50 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0805, 0.7 mm



| General Information | |
|--------------------------|--|
| Series | SMD Comm X7R |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Class II |
| Features | Temperature Stable, Class II |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 11 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|------------|------------------|
| Chip Size | 0805 |
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| Т | 0.78mm +/-0.10mm |
| S | 0.7mm MIN |
| В | 0.5mm +/-0.25mm |
| | |

| Т | 0.78mm +/-0.10mm |
|--------------------------|------------------|
| S | 0.7mm MIN |
| В | 0.5mm +/-0.25mm |
| | |
| Packaging Specifications | |

4000

Packaging

Packaging Quantity

T&R, 180mm, Paper Tape

| Specifications | |
|--|--|
| Capacitance | 0.012 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 2.5% 1 kHz 1.0 Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 83.3333 GOhms |

| Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and |
|--|
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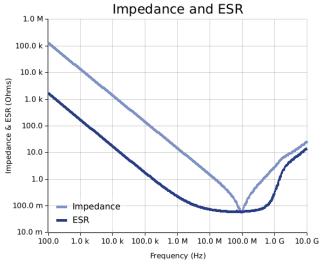
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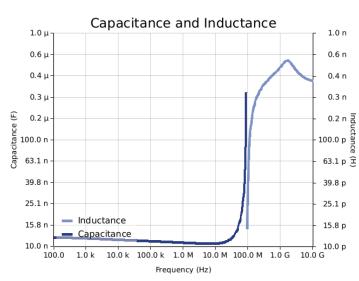


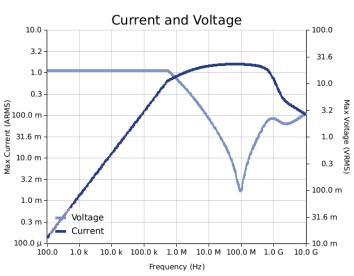
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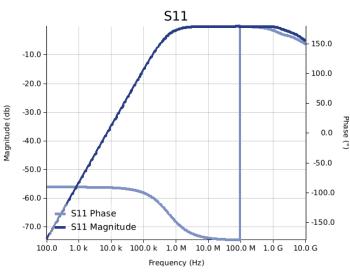
Simulations

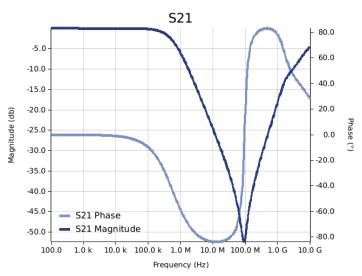
For the complete simulation environment please visit K-SIM.

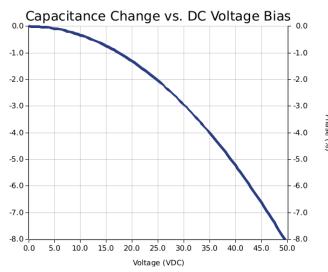










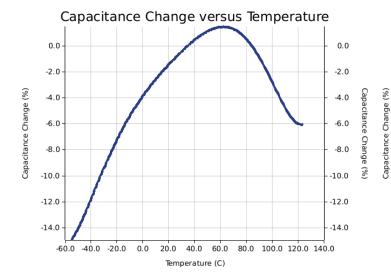


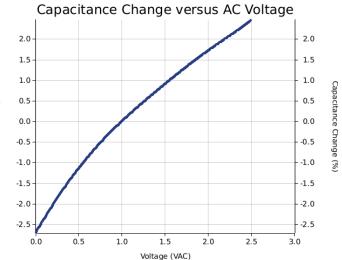
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Phase (%)



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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.

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